Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (previously presented) A module with a chip with chip connection contacts said module having a mid-point and said module being envisaged for use in a data carrier designed for contactless communication, that data carrier containing the module with the chip with chip connection contacts and additionally at least one further electrical component connected in an electrically conductive manner with the chip with component connection contacts wherein the electrically conductive connection between the chip and the at least one further component can be realized in accordance with two opposed polarities, and

wherein the module has a chip with at least two pairs of chip connection contacts and wherein the module has at least two pairs of module connecting plates wherein the two module connecting plates of each pair are provided for the electrically conductive connection with the component connection contacts of in each case one of at least two further components (12, 13), and wherein each module connecting plate has a plate surface with a particular shape and is designed to be electrically conductive and is connected in an electrically conductive manner with a chip connection contact and wherein the shapes of the plate surfaces of the two module connecting plates of each pair are identical, and wherein the shapes of the plate surfaces of the module connecting plates of different pairs are different, and wherein in a starting position of the module connecting plates, the shapes of the plate surfaces of the module connecting plates result in a particular plate pattern and differ such that when, starting from the starting position, all the module connecting plates are jointly rotated around an axis that runs perpendicular in relation to the plate surfaces and that passes through the mid-point the same plate pattern always results after joint rotation around 180° in each case.

2. (previously presented) A module as claimed in claim 1, wherein the module has a main axis running through the mid-point and wherein of each pair of module connecting plates, one module connecting plate points in a first direction that runs parallel to the main axis and points away from the mid-point and the other module connecting plate points in a second direction that runs parallel to the main axis and runs opposite to the first direction and points away from the mid-point and wherein the module connecting plates that point in the first direction lie next to one another and are separated from one another by a separation zone in each case, and wherein the module connecting plates that point in the second direction lie next to one another and are separated from one another by a separation zone in each case, and wherein the shapes of the plate surfaces of two module connecting plates lying next to one another are different.

3. (previously presented) A module as claimed in claim 2, wherein the shapes of the plate surfaces of two module connecting plates lying next to one another are different as a consequence of the characteristics of the separation zone that separates these two module connecting plates.

4. (previously presented) A module as claimed in claim 3, wherein at least one separation zone lying between two module connecting plates that lie next to one another runs obliquely to the main direction.

5. (previously presented) A module as claimed in claim 4, wherein the separation zone runs in a straight line.

6. (previously presented) A module as claimed in claim 1, wherein the module connecting plates have been produced with the aid of a conductor frame configuration.

7. (previously presented) A data carrier that is designed for contactless communication and contains a module with a chip with chip connection contacts and additionally at least one further electrical component connected in an electrically

conductive manner with the chips with component connection contacts and wherein the module is designed as claimed in claim 1, and

wherein the module connecting plates of each pair of module connecting plates is connected with the component connection contacts of in each case one of at least two further components.

8. (previously presented) A lead frame configuration which is provided for the production of a module as claimed in claim 1 and which has a mid-point,

wherein the lead frame configuration has at least two pairs of module connecting plates

wherein the two module connecting plates of each pair are intended for the electrically conductive connection with the component connection contacts of in each case one of at least two further components and wherein each module connecting plate has a plate surface with a particular shape and is designed to be electrically conductive and is connected in an electrically conductive manner to a chip connection contact and wherein the shapes of the plate surfaces of the two module connecting plates of each pair are identical, and wherein the shapes of the plate surfaces of the module connecting plates of different pairs are different, and wherein in a starting position of the module connecting plates, the shapes of the plate surfaces of the module connecting plates yield a particular plate pattern and differ such that, starting from the starting position, when all the module connecting plates are jointly turned around an axis that runs perpendicular in relation to the plate surfaces and passes through the mid-point the same plate pattern always results after joint turning around 180° in each case.

9. (previously presented) A lead frame configuration as claimed in claim 8, wherein the lead frame configuration has a main axis that passes through the mid-point and wherein of each pair of module connecting plates, one module connecting plate points in a first direction that runs parallel to the main axis and points away from the mid-point and the other module connecting plate points in a second direction that runs parallel to the main axis and runs opposite to the first direction and points away from the mid-point and wherein the module connecting plates that point in the first direction lie next to one

another and are separated from one another by a separation zone in each case, and wherein the module connecting plates that point in the second direction lie next to one another and are each separated from one another by a separation zone in each case, and wherein the shapes of the plate surfaces of two module connecting plates that lie next to one another are different.

10. (previously presented) A lead frame configuration as claimed in claim 9, wherein the shapes of the plate surfaces of two module connecting plates that lie next to one another are different as a consequence of the characteristics of the separation zone that separates these two module connecting plates.

11. (previously presented) A lead frame configuration as claimed in claim 10, wherein at least one separation zone lying between two module connecting plates that lie next to one another runs obliquely to the main direction.

12. (previously presented) A lead frame configuration as claimed in claim 11, wherein the separation zone runs in a straight line.